

REMARKS

Claims 18, 19, 36, 41-43, 87-91, 95-102 and 109-131 are pending. Claims 54-64, 70-77, 79-85 and non-elected claims 103-107 are cancelled without prejudice or disclaimer. New claims 109-131 are added.

Claims 18, 19, 36, 41, 43, 57-64, 71, 79, 81-83, 87-91 and 97-102 were rejected under 35 USC § 102(e) as being anticipated by Kata et al. '337. Favorable reconsideration is earnestly solicited.

In this rejection, the Examiner considers the claimed resin layer as corresponding to the adhesive layer 43 and the organic insulating film 61. It is respectfully submitted that such is not a reasonable interpretation of the claims and of Kata et al. '337.

Adhesive layer 43 and organic insulating film 61 of Kata et al. '337 are separate elements which can not reasonably be considered to correspond to the claimed resin layer which is formed on the surface of the semiconductor element and seals at least a lateral surface of the protruding electrodes, wherein the lead lines are located between the semiconductor element and the resin layer.

It is presumed that it is the Examiner's position that separate elements can be considered to form a single element. However, even if the Examiner is permitted to consider the adhesive layer 43 and organic insulating film 61 to correspond to the claimed resin layer, such a "resin layer" would fail to meet the limitations set forth in the claims. Specifically, for example, claim 18 requires the lead lines to be located between the semiconductor element and the resin layer. If the resin layer is considered to include the adhesive layer 43, then the lead line of Kata et al. '337 can not be considered to be located between the semiconductor element and the resin layer.

Furthermore, the adhesive layer 43 is not a compressed sealing resin as required by the claims. Furthermore, the electrode plate 60 is not provided in the compressed sealing resin.

Claim 42 was rejected under 35 USC § 102(b) as being unpatentable over Kata et al. '942. In this rejection, the Examiner argues that Kata et al. '942 provides a first resin layer 3 that is formed on the surface of the semiconductor element and seals lateral surfaces of the protruding electrodes. However, it does not appear that the resin layer 3 of Kata et al. '942 is formed on the surface of the semiconductor element. For at least this reason, Kata et al. '942 would not anticipate claim 42.

The rejections of claims 54-56 under 35 USC § 102(e) as being anticipated by Kitahara '363 have been rendered moot.

An Information Disclosure Statement is filed herewith. The Examiner is requested to acknowledge consideration of the Information Disclosure Statement in the next communication from the Patent Office.

For at least the foregoing reasons, the claimed invention distinguishes over the cited art and defines patentable subject matter. Favorable reconsideration is earnestly solicited.

Should the Examiner deem that any further action by Applicants would be desirable to place the application in condition for allowance, the Examiner is encouraged to telephone Applicants' undersigned attorney.

Applicants: **FUKASAWA et al**  
Serial No.: **09/029,608**

Docket No.: **980233**  
Group Art Unit: **2814**

In the event that this paper is not timely filed, applicants respectfully petition for an appropriate extension of time. The fees for such an extension or any other fees which may be due with respect to this paper, may be charged to Deposit Account No. 01-2340.

Respectfully submitted,

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